

Fig. 1

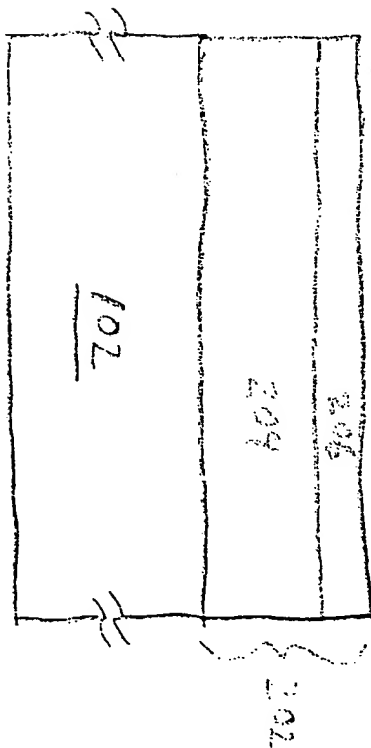


Fig. 2

00639626 004500

17195

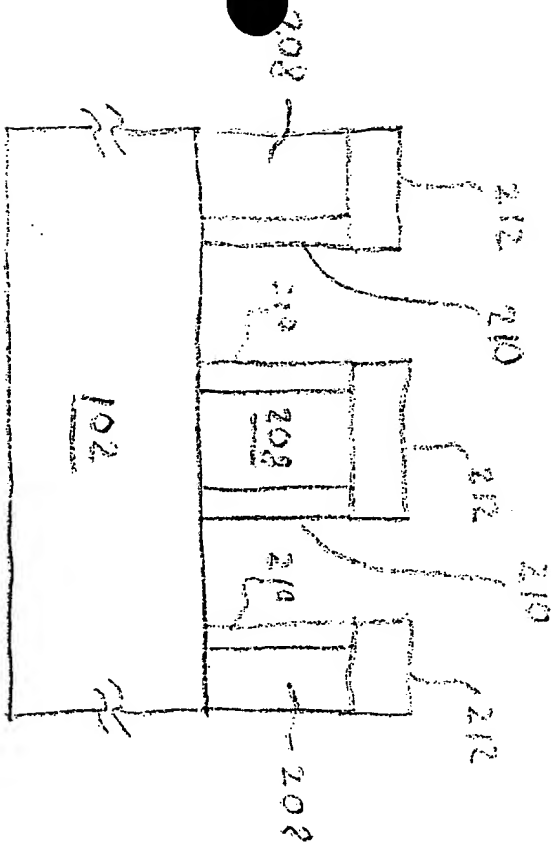


Fig. 3

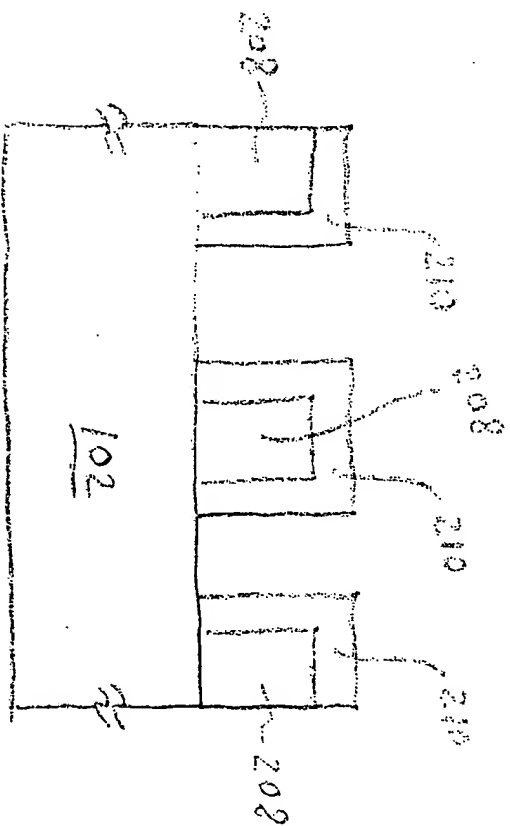


Fig. 4

00630626, 084600

P7195

Species	As Deposited (counts/second)	10 second exposure (counts/second)	60 second exposure (counts/second)
F	59.16	12.53	9.98
CF	0.86	0.05	0.03
F <sub>2</sub>	1.96	0.11	0.09
CF <sub>2</sub>	0.61	0.04	0.03
CF <sub>3</sub>	0.08	0.07	0.07

Fig. 5

005120" 32306320

Place wafer having fluorinated low-k material into a reaction chamber

### Flow reducing plasma source gases

### Ignite reducing plasma

Terminate exposure to reducing plasma after predetermined time

**Fig. 6**

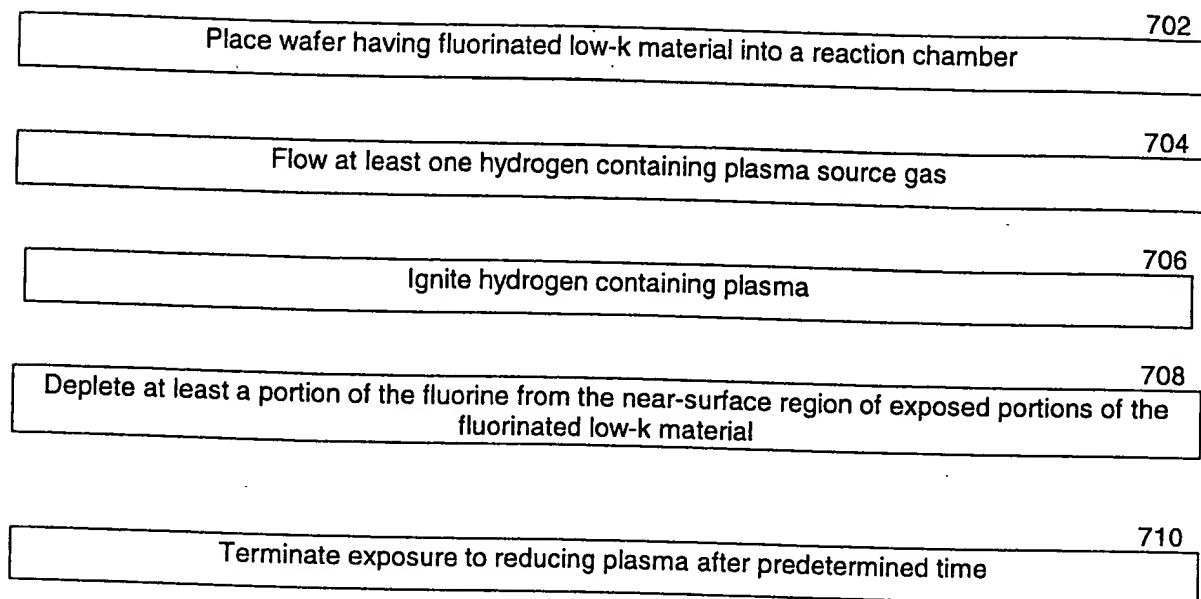


Fig. 7

005480 094500